

## 74ABT126 Quad Buffer with 3-STATE Outputs

### General Description

The ABT126 contains four independent non-inverting buffers with 3-STATE outputs.

### Features

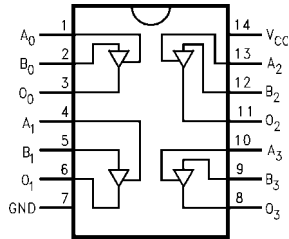
- Non-inverting buffers
- Output sink capability of 64 mA, source capability of 32 mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability
- Disable time less than enable time to avoid bus contention

### Ordering Code:

Order Number	Package Number	Package Description
74ABT126CSC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow Body
74ABT126CSJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT126CMTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

### Connection Diagram



### Pin Descriptions

Pin Names	Descriptions
$A_n, B_n$	Inputs
$O_n$	Outputs

### Function Table

Inputs		Output
$A_n$	$B_n$	$O_n$
H	L	L
H	H	H
L	X	Z

H = HIGH Voltage Level  
L = LOW Voltage Level  
Z = HIGH Impedance  
X = Immaterial

**Absolute Maximum Ratings** (Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Any Output in the Disabled or Power-Off State	-0.5V to 5.5V
in the HIGH State	-0.5V to V <sub>CC</sub>
Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)
DC Latchup Source Current (Across Comm Operating Range)	-300 mA
Over Voltage Latchup (I/O)	10V

**Recommended Operating Conditions**

Free Air Ambient Temperature	-40°C to +85°C
Supply Voltage	+4.5V to +5.5V
Minimum Input Edge Rate ( $\Delta V/\Delta t$ )	
Data Input	50 mV/ns
Enable Input	100 mV/ns

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**DC Electrical Characteristics**

Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized HIGH Signal
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage			-1.2	V	Min	I <sub>IN</sub> = -18 mA
V <sub>OH</sub>	Output HIGH Voltage	2.5			V	Min	I <sub>OH</sub> = -3 mA
		2.0			V	Min	I <sub>OH</sub> = -32 mA
V <sub>OL</sub>	Output LOW Voltage			0.55	V	Min	I <sub>OL</sub> = 64 mA
I <sub>IH</sub>	Input HIGH Current			1	μA	Max	V <sub>IN</sub> = 2.7V (Note 3)
				1	μA	Max	V <sub>IN</sub> = V <sub>CC</sub>
I <sub>BVI</sub>	Input HIGH Current Breakdown Test			7	μA	Max	V <sub>IN</sub> = 7.0V
I <sub>IL</sub>	Input LOW Current			-1	μA	Max	V <sub>IN</sub> = 0.5V (Note 3)
				-1	μA	Max	V <sub>IN</sub> = 0.0V
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA, All Other Pin Grounded
I <sub>OZH</sub>	Output Leakage Current			10	μA	0 - 5.5V	V <sub>OUT</sub> = 2.7V; $\overline{OE}_n = 2.0V$
I <sub>OZL</sub>	Output Leakage Current			-10	μA	0 - 5.5V	V <sub>OUT</sub> = 0.5V; $\overline{OE}_n = 2.0V$
I <sub>OS</sub>	Output Short-Circuit Current	-100		-275	mA	Max	V <sub>OUT</sub> = 0.0V
I <sub>CEX</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
I <sub>ZZ</sub>	Bus Drainage Test			100	μA	0.0	V <sub>OUT</sub> = 5.5V; All Others GND
I <sub>CCH</sub>	Power Supply Current			50	μA	Max	All Outputs HIGH
I <sub>CCL</sub>	Power Supply Current			15	mA	Max	All Outputs LOW
I <sub>CCZ</sub>	Power Supply Current			50	μA	Max	$\overline{OE}_n = V_{CC}$ ; All Others at V <sub>CC</sub> or Ground
I <sub>CCT</sub>	Additional I <sub>CC</sub> /Input	Outputs Enabled		1.5	mA	Max	V <sub>I</sub> = V <sub>CC</sub> - 2.1V
		Outputs 3-STATE		1.5	mA		Enable Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V
		Outputs 3-STATE		50	μA		Data Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V All Others at V <sub>CC</sub> or Ground
I <sub>CCD</sub>	Dynamic I <sub>CC</sub> (Note 3)	No Load		0.1	mA/ MHz	Max	Outputs Open $\overline{OE}_n = GND$ , (Note 4) One Bit Toggling, 50% Duty Cycle

**Note 3:** Guaranteed, but not tested.

**Note 4:** For 8 bits toggling, I<sub>CCD</sub> < 0.8 mA/MHz.

## AC Electrical Characteristics

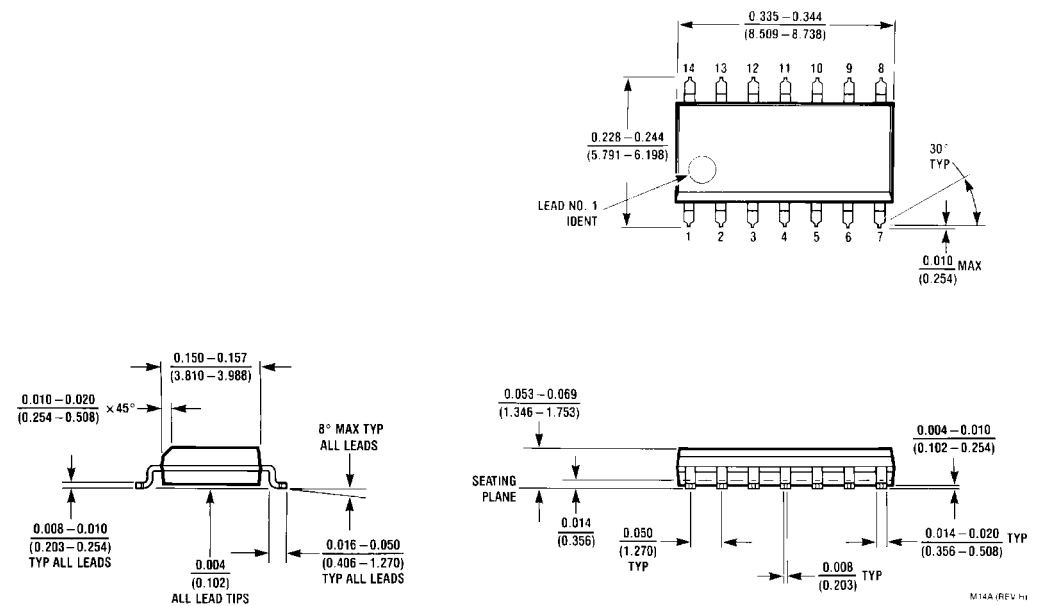
Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5\text{V}$ $C_L = 50\text{ pF}$			$T_A = -40^\circ\text{C to } +85^\circ\text{C}$ $V_{CC} = 4.5\text{V}-5.5\text{V}$ $C_L = 50\text{ pF}$		Units
		Min	Typ	Max	Min	Max	
$t_{PLH}$	Propagation Delay	1.0		4.4	1.0	4.4	ns
$t_{PHL}$	Data to Outputs	1.0		4.6	1.0	4.6	
$t_{PZH}$	Output Enable	1.0		6.5	1.0	6.5	ns
$t_{PZL}$	Time	1.0		6.5	1.0	6.5	
$t_{PHZ}$	Output Disable	1.0		5.8	1.0	5.8	ns
$t_{PLZ}$	Time	1.0		5.5	1.0	5.5	

## Capacitance

Symbol	Parameter	Typ	Units	Conditions $T_A = 25^\circ\text{C}$
$C_{IN}$	Input Capacitance	5.0	pF	$V_{CC} = 0\text{V}$
$C_{OUT}$ (Note 5)	Output Capacitance	9.0	pF	$V_{CC} = 5.0\text{V}$

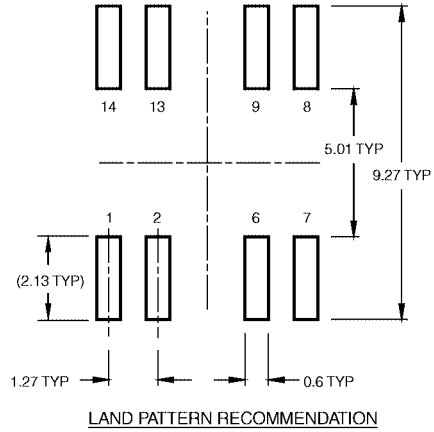
**Note 5:**  $C_{OUT}$  is measured at frequency  $f = 1\text{ MHz}$ , per MIL-STD-883, Method 3012.

**Physical Dimensions** inches (millimeters) unless otherwise noted

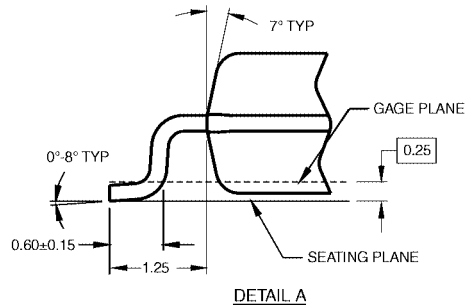
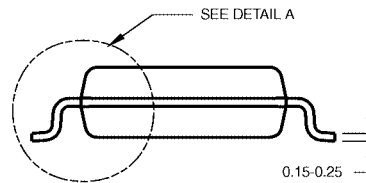


**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow Body  
Package Number M14A**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

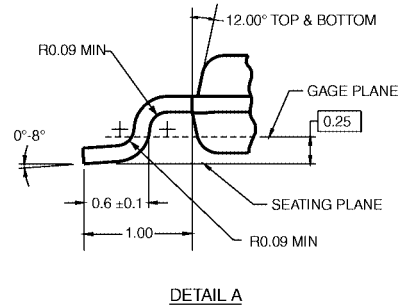
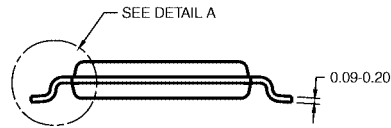
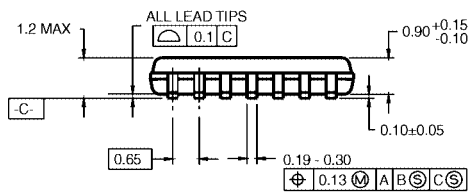
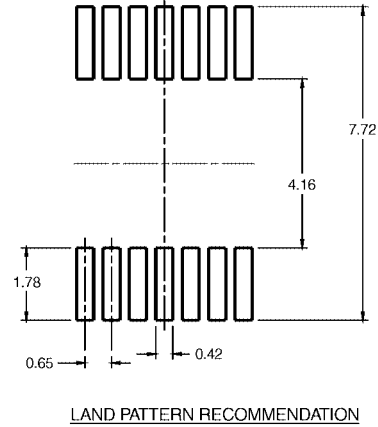
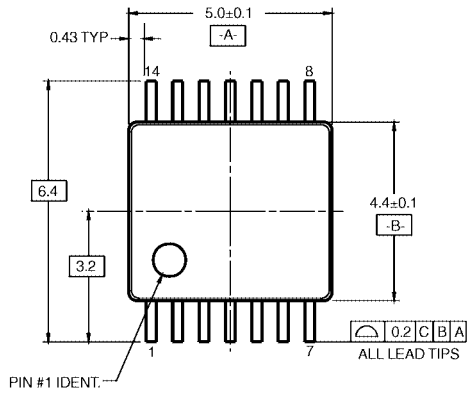


- NOTES:  
A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.  
B. DIMENSIONS ARE IN MILLIMETERS.  
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1

**14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M14D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



- NOTES:  
 A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.  
 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.  
 D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC14RevC3

**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14**

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